

May 2001

# FQT4N20

## 200V N-Channel MOSFET

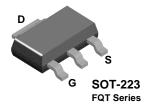
## **General Description**

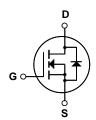
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supply, DC-AC converters for uninterrupted power supply, motor control.

#### **Features**

- 0.85A, 200V, R<sub>DS(on)</sub> = 1.4 $\Omega$  @V<sub>GS</sub> = 10 V Low gate charge ( typical 5.0 nC)
- Low Crss (typical 5.0 pF)
- Fast switching
- · Improved dv/dt capability





# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

	<b>U</b>				
Symbol	Parameter		FQT4N20	Units	
V <sub>DSS</sub>	Drain-Source Voltage		200	V	
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°	°C)	0.85	Α	
	- Continuous (T <sub>C</sub> = 70°	°C)	0.68	Α	
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	3.4	А	
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	52	mJ	
I <sub>AR</sub>	Avalanche Current	(Note 1)	0.85	А	
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	0.22	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns	
$P_{D}$	Power Dissipation (T <sub>C</sub> = 25°C)		2.2	W	
	- Derate above 25°C		0.018	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C	
TL	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	
'L			300		

## **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		57	°C/W

<sup>\*</sup> When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.24		V/°C
I <sub>DSS</sub>		V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 160 V, T <sub>C</sub> = 125°C			10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	racteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.425 A		1.12	1.4	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 0.425 A (Note 4)		1.08		S
C <sub>iss</sub>	Input Capacitance Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		170 35	220 45	pF pF
C <sub>rss</sub>	Reverse Transfer Capacitance			5	7	pF
Switchi	ng Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 100 V, I <sub>D</sub> = 3.6 A,		7	25	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$		50	110	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			7	25	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4, 5)		25	60	ns
$Q_g$	Total Gate Charge	$V_{DS} = 160 \text{ V}, I_{D} = 3.6 \text{ A},$		5.0	6.5	nC
$Q_{gs}$	Gate-Source Charge	V <sub>GS</sub> = 10 V		1.4		nC
$Q_{gd}$	Gate-Drain Charge	(Note 4, 5)		2.1		nC
Drain-S	Source Diode Characteristics ar	nd Maximum Ratings				
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				0.85	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				3.4	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 0.85 A			1.5	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 3.6 \text{ A},$		90		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$ (Note 4)		0.24		μC

- **Notes:**1. Repetitive Rating: Pulse width limited by maximum junction temperature 2. L = 108mH, I<sub>AS</sub> = 0.85A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25  $\Omega$ , Starting T<sub>J</sub> = 25°C 3. I<sub>SD</sub>  $\leq$  3.6A, di/dt  $\leq$  300A/µs, V<sub>DD</sub>  $\leq$  BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C 4. Pulse Test: Pulse width  $\leq$  300µs, Duty cycle  $\leq$  2% 5. Essentially independent of operating temperature

# **Typical Characteristics**

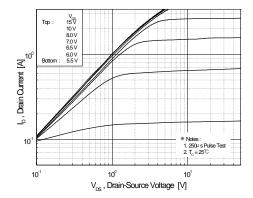


Figure 1. On-Region Characteristics

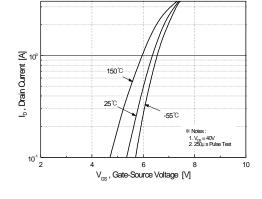


Figure 2. Transfer Characteristics

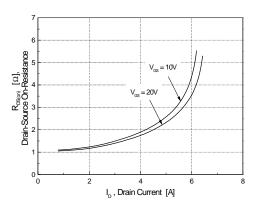


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

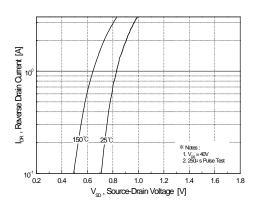


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

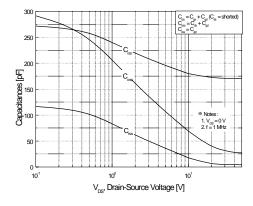


Figure 5. Capacitance Characteristics

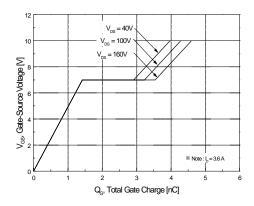
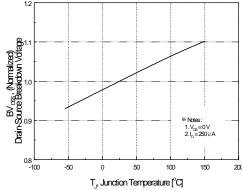


Figure 6. Gate Charge Characteristics

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# Typical Characteristics (Continued)



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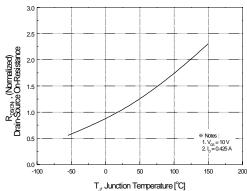
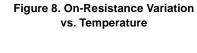
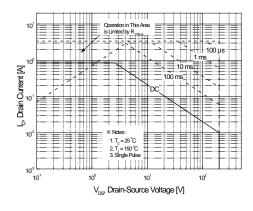


Figure 7. Breakdown Voltage Variation vs. Temperature





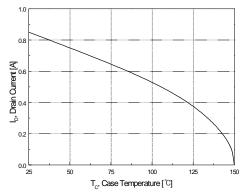


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

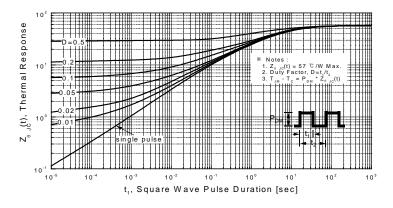
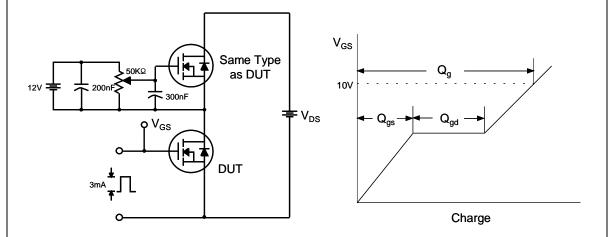


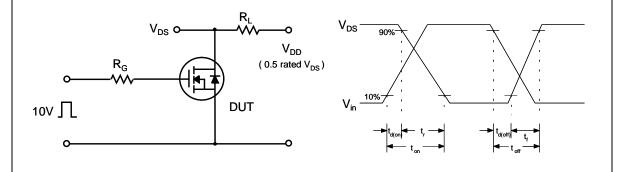
Figure 11. Transient Thermal Response Curve

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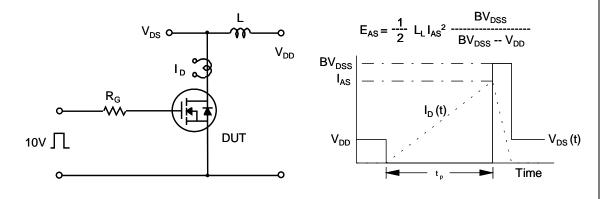
## **Gate Charge Test Circuit & Waveform**



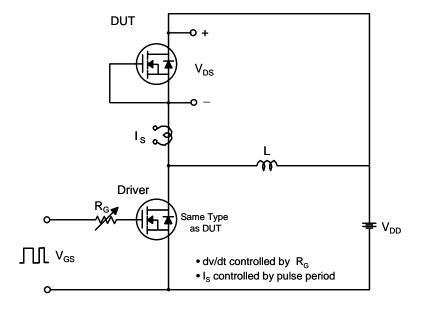
## **Resistive Switching Test Circuit & Waveforms**

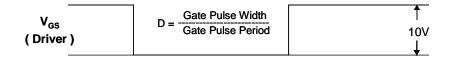


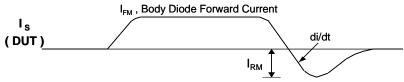
## **Unclamped Inductive Switching Test Circuit & Waveforms**



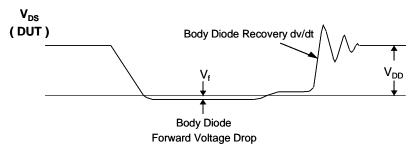
### Peak Diode Recovery dv/dt Test Circuit & Waveforms





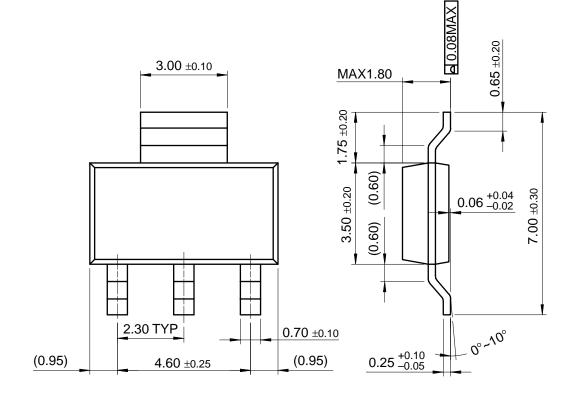


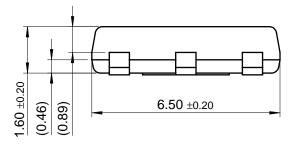
Body Diode Reverse Current



# **Package Dimensions**

# SOT-223





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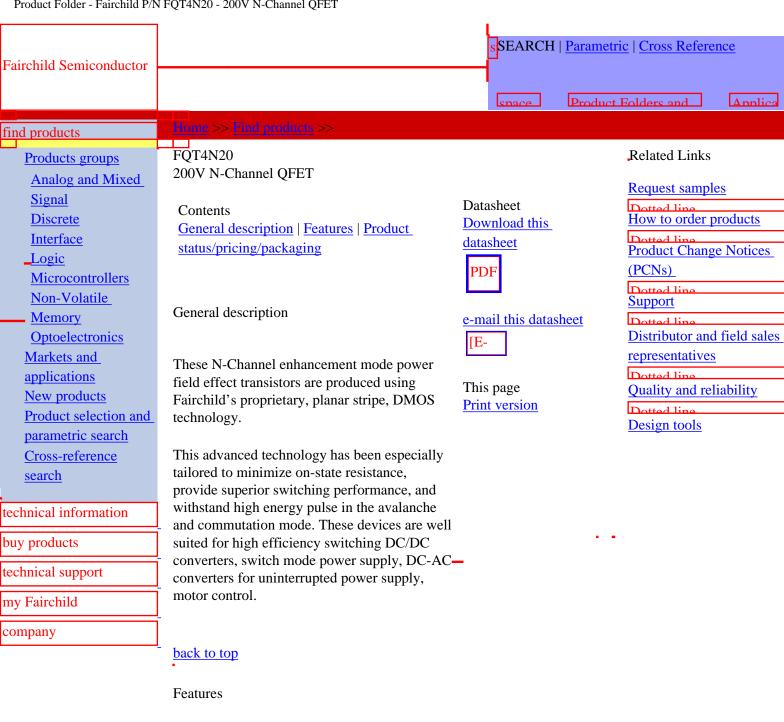
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- 0.85A, 200V
  - $R_{DS(on)} = 1.4\Omega @V_{GS} = 10 \text{ V}$
- Low gate charge (typical 5.0 nC)
- Low Crss (typical 5.0 pF)
- Fast switching
- Improved dv/dt capability

### back to top

Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
		,		,	

Product Folder - Fairchild P/N FQT4N20 - 200V N-Channel QFET

FQT4N20TF	Full Production	\$0.322	SOT-223	3	TAPE REEL

<sup>\* 1,000</sup> piece Budgetary Pricing

back to top

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